

SPECIFICATION

Cusion	iici.					
				Receipt		
Item:		Crysta	al Unit	,		
Type: NX503			32GA			
Freque	ency	8.000	MHz			
Custor	mer's Spec. No	D.:				
NDK S	Spec. No.:	STD-C	CSU-1			
Charge	e:					
Sales				Approved	H.Kobayashi	
		1st Eng. Dont	Tel.	Checked		
Engine	er	1 st Eng. Dept. K.Nakashima	(81)-4-2900-6631	1 Drawn	K.Nakashima	
		F	Revision Record			
Rev.	Rev. Date	Items		tents	Remarks	
	16. Apr. 2013	Issue				

1. Customer specifications number :

2.NDK specification number : STD-CSU-1 3.Type : NX5032GA

4. Electrical characteristics

4.1 Nominal frequency : 8.000 MHz
4.2 Overtone order : Fundamental

4.3 Frequency tolerance : $\pm 50 \times 10^{-6}$ max. (+25 °C)

4.4 Frequency versus : $\pm 150 \times 10^{-6}$ max. (-40~+150 °C)

temperature characteristics

The reference temperature shall be 25°C

 $4.5 \ \mbox{Equivalent resistance} \qquad \qquad : 300 \ \mbox{Qmax}. \\ 4.6 \ \mbox{Maximum level of drive} \qquad \qquad : 500 \ \mbox{μWmax}.$

4.7 Insulation resistance : Terminal to terminal insulation resistance also

terminal to cover insulation resistance must be $500M\Omega$ (min) when DC100V $\pm 15V$ is applied.

5. Measurement circuit

5.1 Frequency measurement

*Measuring instrument : π -Network
* Load capacitance(C_L) : 8pF
*Level of drive : 10μ W

5.2 Equivalent resistance measurement

* Measuring instrument : π -Network
* Load capacitance(C_L) : Series
*Level of drive : $10\mu W$

6. Other performances

6.1 Storage temperature range : -40~+150°C

6.2 Air-tightness : Less than 3×10⁻⁹Pa m³/s (Helium leak detector)

7. Examination results document

Since a performance is guaranteed, an examination results document does not submit.

8. Application drawing

8.1 External dimension: EXD14B-000168.2 Taping and reel figure: EXK17B-000278.3 Holder marking: EXH11B-001428.4 Reliability assurance Item: EXS30B-003968.5 Recommendation reflow profile: EXS30B-00344

9. Notice

- 9.1. Order items are manufactured according to specification. As to conditions, which are not indicated in this specification and unpredictable such as applied condition and oscillation margin, please check them beforehand.
- 9.2. Crystal units will be damaged by ultrasonic welding process due to resonance of crystal wafer itself. NDK does not recommend using ultrasonic welding. If Ultra Sonic welding used, NDK strongly recommend verifying crystal unit damage by ultrasonic weld.
- 9.3.Unless we receive request for modification within 3 weeks from the issue date of this NDK specification sheet, we will supply products according to this specification. Also, if you'd like to modify specification of order, which has been placed with delivery request within 3 weeks from the issue data of this specification sheet, we would like to discuss with you separately.
- 9.4. In no event shall the company be liable for any product failure resulting from an inappropriate handling or operation of the product beyond the scope of its guarantee.
- 9.5. Where any change to the process condition is made due to the change(s) in the production line, inform personnel of the specifications.
- 9.6. Should this specification data give rise to any disputes relating to any intellectual property rights or any other rights of a third person, the company shall not indemnify anyone for any damage. Their disclosure must not be construed as the grant of a license to use any of the intellectual property rights owned by the company.
- 9.7. If you intend to use products listed on this specification for applications that may result in loss of life or assets (controls relating to safety, medical equipment, aeronautical equipment, space equipment, etc.), please do not fail to advise us of your intention beforehand.
- 9.8. In the company's production process whatever amount of ozone depleting substances (ODS) as specified in the Montreal protocol is not used.
- 9.9. Information contained in this specification must not be quoted, reproduced or used for other purposes including processing either in part or in full without obtaining prior approval from the company.
- 9.10. The appearance color has a different case by purchasing it more than 2 suppliers of the component, but characteristic and reliability are guaranteed.

10. Prohibited items

Be sure to use the product under the following conditions. Otherwise, the characteristics deterioration or destruction of the product may result.

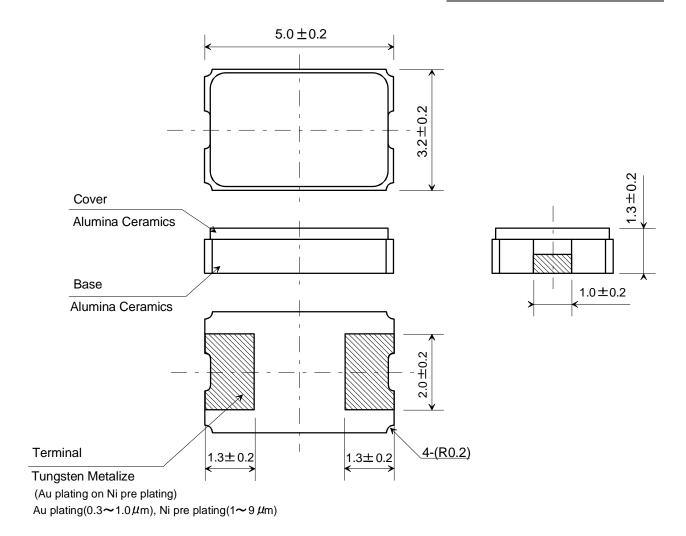
(1)Reflow soldering heat resistance

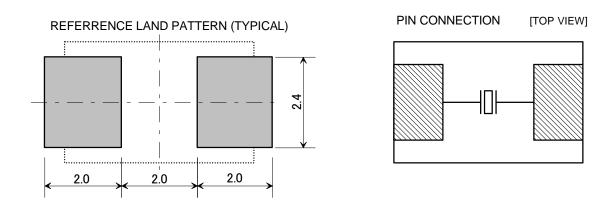
Peak temperature: 265°C, 10 sec Heating: 230°C or higher, 40 sec Preheating: 150°C to 180°C, 120 sec

Reflow passage times: twice (2)Manual soldering heat resistance

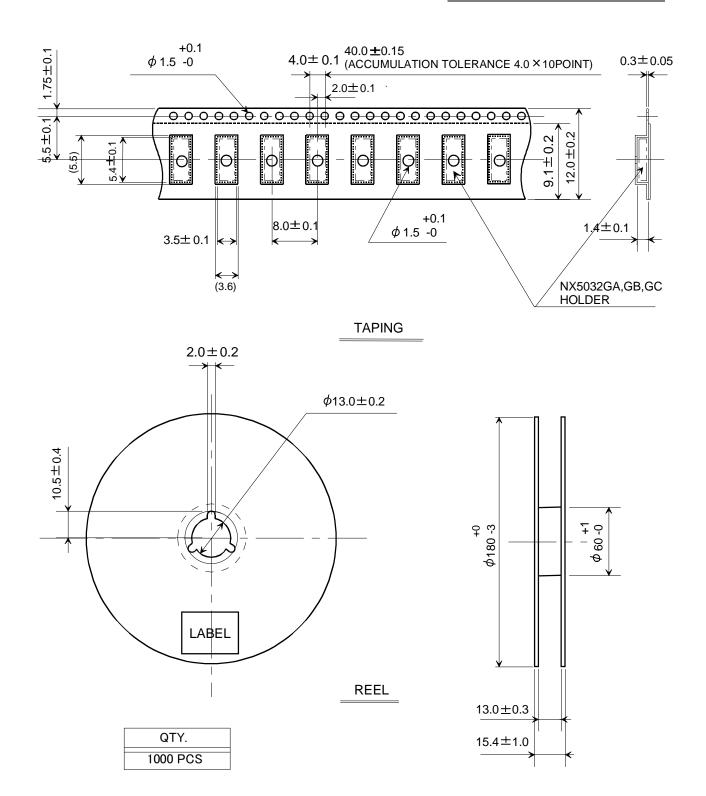
Pressing a soldering iron of 400°C on the terminal electrode for four seconds (twice).

When using a soldering iron, press its tip on the part below the sealed part, avoiding the glass-sealed part (otherwise, the glass will melt and air-tightness may be lost).

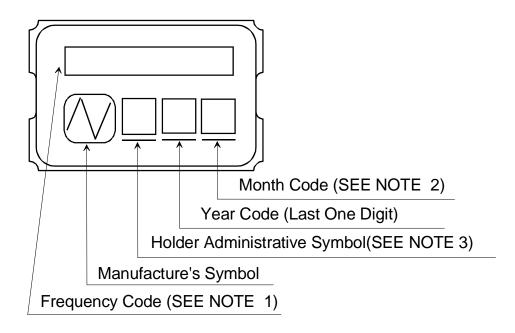




	Date of Revise Charge		Charge	Approved	Reason				
Е	15	.Sep.2006	N.Yamamoto	K.Kubota	Chang	ge refere	ference land pattern size		
		Date	Name	Third Angle Proje	ection	-	Tolerance S		ale
Drav	wn	19.Mar.1999	Y.Morizumi	Dimension:m	m			/	1
Des	signed 19.Mar.1999 Y.Morizumi Title			Drawing No.		Rev.			
Checked		19.Mar.1999	M.Miura	NX5032GA External		EVD44B	00046	Г	
Approved		19.Mar.1999	M.Okamoto	Dimension		EXD14B-00016		E	



	Dat	e of Revise	Charge	Approved	Reason	1			
С	19	.Dec.2008	K.Oguri	K.Miyashita	Addition	ddition of NX5032GB, GC			
		Date	Name	Third Angle Proje	ection	n Tolerance		Tolerance Sca	
Draw	vn	13.Jul.1999	Y.Morizumi	Dimension:m	ım			/	
Designed 13.Jul.1999		13.Jul.1999	Y.Morizumi	Title			Drawing No.		Rev.
Checked				Crystal Holder Packing		EXK17B-	00027	_	
App	roved	13.Jul.1999	M.Okamoto	Crystal Hold	er Pack	king	EXKI/D.	-00027	С



NOTE 1. Frequency Code

Marking Frequency is consist of five digits, first five digits of Nominal Frequency

Example

Nominal Frequency	28.636363 MHz				
Frequency Code	28.636				

2. Month Code Table

Month	1	2	3	4	5	6	7	8	9	10	11	12
	Jan.	Feb.	Mar.	Apr.	May.	Jun.	Jul.	Aug.	Sep.	Oct.	Nov.	Dec.
Month Code	1	2	3	4	5	6	7	8	9	Х	Υ	Z

3. Marking contents

Administrative symbol | S

*Marking digits are not include a decimal point and dot mark.

	Dat	e of Revise	Charge	Approved	Reason					
В	20	.Sep.2005	N.Fukurai	K.Kubota	Change	Change Representation				
		Date	Name	Third Angle Proje	ection Tolerance			Sca	Scale	
Draw	/n	16.Jul.2002	Y.Sakurai	Dimension:m	mm		/	/		
Desi	igned	16.Jul.2002	Y.Sakurai	Title			Drawing No.		Rev.	
Che	cked	16.Jul.2002	M.Miura	Crystal Hald	or Mork	rin a	EXH11B-	00442	0	
Аррі	roved	16.Jul.2002	T.Ishii	Crystal Hold	er wark	ang	EVUIID.	-00142	В	

Reliability assurance item

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N.I.	T	T	(page: 1/2)
No.	Test item	Test methods	Spec. code
1	Drop	Devices are dropped from the height 75 cm onto iron plate. Execution 3 times random drops.	А
2	Shock	Acceleration: 49000 m/s ² Duration: 0.15 ms Half-Sine pulse 1 Shocks in 6 mutually perpendicular planes, Total 6 shocks	Α
3	Vibration	Frequency range: 10 to 2000 Hz Amplitude or Acceleration: 1.52 mm or 196 m/s ² Sweep time: 20 min Test time: $4 \text{ h} \times 3$	А
4	Electrode adherent strength	See remark (1)	В
5	Solderability	Pre-heat temperature : $150 ^{\circ}\text{C}$ Pre-heat Time : $60 ^{\circ}$ 120 s Peak temperature : $240 \pm 5 ^{\circ}\text{C}$ 215 °C Over time : $10 ^{\circ}$ 30 s	С
6	Resistance to soldering heat	$\begin{array}{lll} \mbox{Pre-heat temperature} & : 150 \ \mbox{°C} \\ \mbox{Pre-heat time} & : 60 \ \mbox{\sim} \ 120 \ \mbox{s} \\ \mbox{Test temperature} & : 260 \pm 5 \ \mbox{°C} \\ \mbox{Test time} & : 10 \pm 1 \ \mbox{s} \\ \end{array}$	A,B
7	Resistance to cold	Leave at -40±2 °C for 1000 h	Α
8	Resistance to heat	Leave at +150±2 °C for 1000 h	А
9	Humidity	Device are left in temperature at +85 ± 2 °C with relative humidity of 80~85 % for 1000 h	A,D
10	Thermal shock	Device are left into the following temperature cycle as shown in (Figure1) for 1000 consecutive cycle. 150±5 °C 25 °C -40±5 °C 30 min (Figure1)	A,B

Reliability assurance item

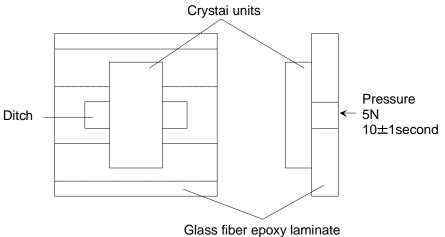
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Spec. code	Specification
А	Frequency tolerance and series resistance should be cleared.
В	After testing unless cracking of materials view of eyes and unless break of seal.
С	The leads shall acquire a new solder coat cover at 90 % of immersed area.
D	Insulation resistance shall be greater than 500 M Ω

Remark (1) Electrode adherent strength.

1) Test method condition

Using the solder, soldering Iron or reflow soldering bath shall be used for soldering on test fixture (Glass fiber epoxy laminate: Thickness 1.6mm+/-0.2mm) shown below.



2) Specified value

No peel of electrode, no crack, no other abnormality

Recommendation reflow condition

1.IR reflow condition

